This document can handle board shapes up to 7x9m x 10m, although our panel vendors top out at 7x10m.

To resize the board shape, do the following:

1. Select 'jumps on ml board outline' and delete entire in single layer mode...shift+Space.
2. Draw a rectangle using lines (Example will be for a 4x6 board)
   - Enter Place Line mode (keyboard p)
   - keyboard j to jump to original, hit enter
   - keyboard j to jump to location, set x to 0,000, hit enter twice
   - keyboard j to jump to location, set y to 0,000 and y to 4,000, hit enter twice
   - keyboard j to jump to location, set x to 0 and y to 4,000, hit enter twice
   - keyboard j to jump to original, hit enter

If you resize the board, don't forget to save the drill table strings on the Drill Drawing layer...they should be just to the right of your board shape.
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